



1GHz ÷ 16/17, ÷32/33 Multi-Modulus Divider

DS3651 Issue 2.4 June 1999

Features

- Advanced Resynchronisation techniques to negate loop delay effects
- CMOS compataible output capability
- Multi-Modulus division
- Available as DESC SMD 5962-9208901MPA

Odering Information

SP8782 A DG SP8782 B MP

DES9208901/AC/DGAZ(SMD)

Description

The SP8782 is a multi-modulus divider which divides by 16/17 when the Ratio Select input is low and by 32/33 when the Ratio Select input is high. When high, the modulus Control input selects the lower division ratio (16 or 32) and the higher ratio (17 or 33) when it is low.

The device uses resynchronisation techniques to reduce the effects of propagation delays in frequency synthesis.

The SP8782A (ceramic DIL package) is characterised over the full military temperature range of -55°C to +125°C, the SP8782B (miniature plastic DIL package) over the industrial range of -40°C to+85°C.

Absolute Maximum Ratings

Supply Voltage 6V Clock input level 2.5V p-p Junction temperature +175°C Storage temperature range:

SP8782A -55°C to +150°C SP8782B -55°C to +125°C

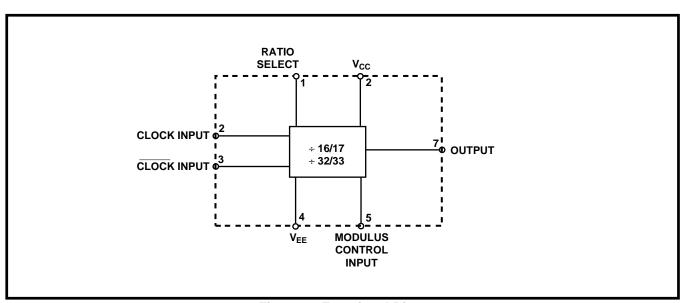


Figure 1 Functional Diagram

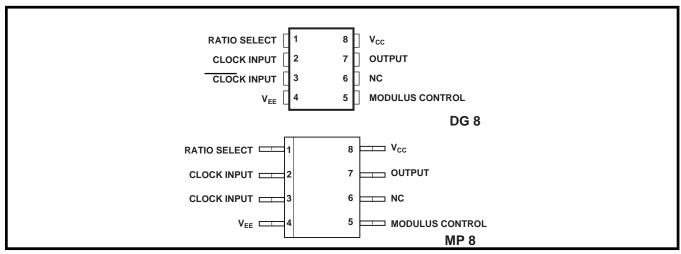


Figure 2 Typical Pin Connections

Electrical Characteristics

Unless otherwise stated, the Electrical Characteristics are guaranteed over the specified supply, frequency and temperature range.

Supply Voltage, $V_{CC} = +4V$ to +5.5V, $V_{EE} = 0V$

Temperature T_{amb}= -55°C to +125°C, (SP8782A), -40°C to +85° C (SP8782B)

Characteristic	Pin Value				Conditions
		Min	Max	Units	
Maximum frequency	2, 3	1		GHz	Input = 200-1200mVp-p
(sinewave input)					
Minimum frequency	2, 3		50	MHz	Input = 400-1200mVp-p
Min Slew rate for low frequency operation	2, 3		100	V/μs	
Power Supply current, I _{cc}	8		60	mA	Output unloaded, V _{cc} =5.5V
Output low voltage	7	0	1.7	V	
Output high voltage	7	V _{cc} -1.4	V _{cc}	V	
Modulus control input high voltage	5	0.7V _{cc}	V _{cc}	V	At driver end of $3k\Omega$ resistor
Modulus control input low voltage	5	0	0.3V _{cc}	V	At driver end of $3k\Omega$ resistor
Modulus control input high current	5	0.6	1.2	mA	Via 3k Ω resistor to V $_{ m cc}$
Modulus control input low current	5	-0.6	-1.2	mA	Via 3k Ω resistor to V $_{cc}$
Ratio select input high voltage	1	0.6V _{cc}	V _{cc}	V	
Ratio selected input low voltage	1	0	0.4V _{cc}	V	
Ratio select input current	1	-10	10	μΑ	
Clock to output propagation Delay	2,3,7		3	ns	
Set-up time, t _s	5,7	3		ns	See note 1 and Fig. 3a
Release time,t,	5,7	3		ns	See note 2 and Fig. 3b
 					_

Notes: 1. The set-up time t_s is defined as the minimum time that can elapse between L \rightarrow H transition of the modulus control input and the next L \rightarrow H output transition to ensure that the \div 16 (32) mode is obtained.

2. The release time t_r is defined as the minimum time that can elapse between $H \rightarrow L$ transition of the modulus control input and the next $L \rightarrow H$ output transition to ensure that the \div 17 (33) mode is obtained.

Modulus control	Ratio select input			
input	0	1		
0	÷17	÷33		
1	÷16	÷32		

Table 1 Truth table for control inputs

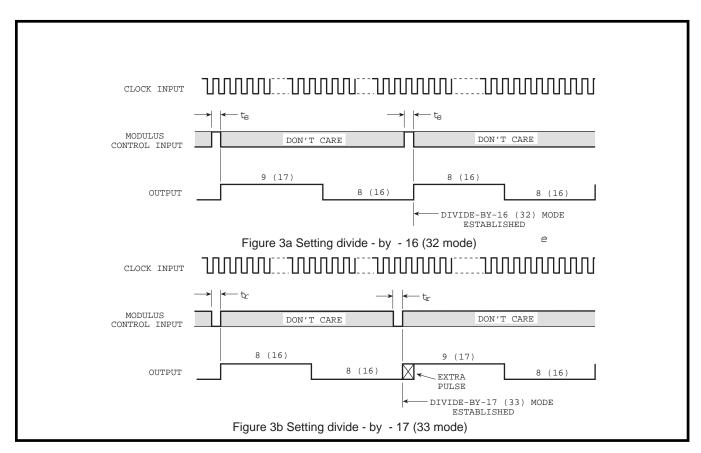


Figure 3 Timing diagrams

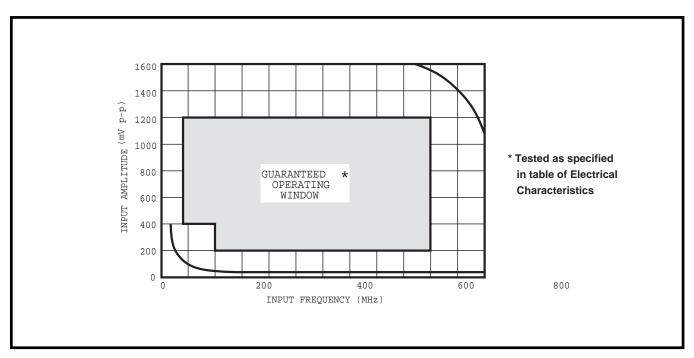


Figure 4 Typical input characteristics

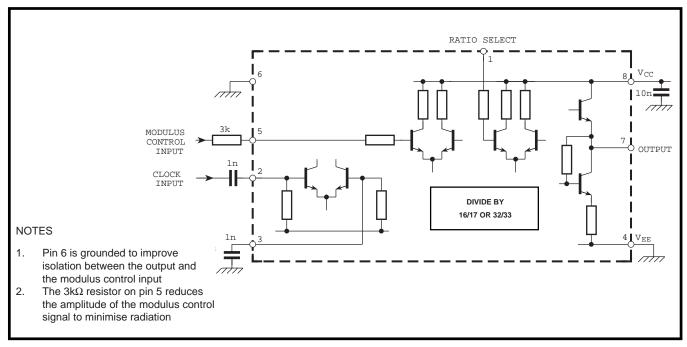


Figure 5 Typical application showing interfacing

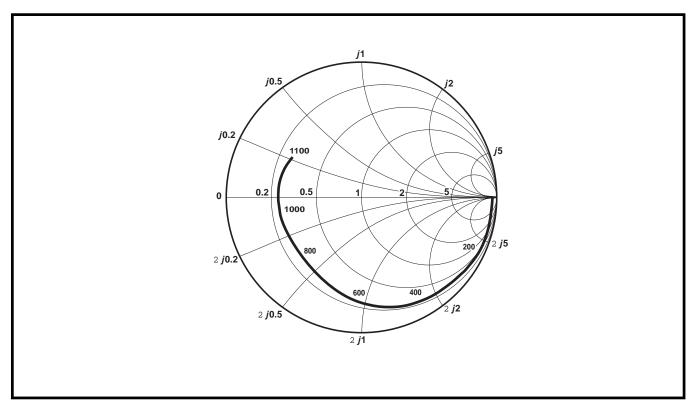
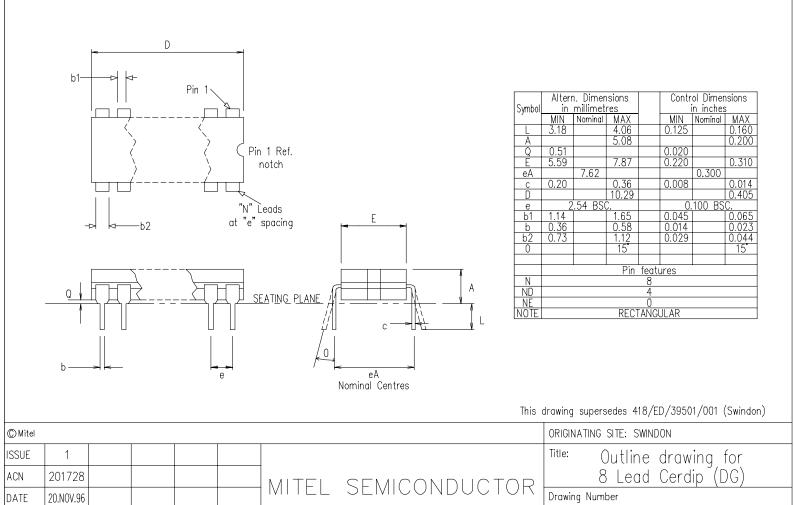
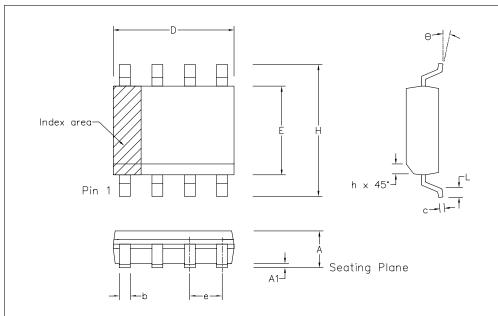


Figure 6 Typical input impedance. Test conditions: supply voltage =5V, ambient temperature =25°C, frequencies in MHz, impedances normalised to 50 Ω



APPROVED

GPD00270



.35).10 80 5.80 5.80	1.75 0.25 5.00 6.20 4.00	0.053 0.004 0.189 0.228 0.150 0.016	0.069 0.010 0.197 0.244 0.157	
).10 80 5.80 5.80	0.25 5.00 6.20 4.00	0.004 0.189 0.228 0.150	0.010 0.197 0.244 0.157	
80 5.80 5.80	5.00 6.20 4.00	0.189 0.228 0.150	0.197 0.244 0.157	
5.80	6.20 4.00	0.228 0.150	0.244 0.157	
5.80	4.00	0.150	0.157	
).40	1.27	0.016	0.000	
		0.010	0.050	
1.27 BSC		0.050 BSC		
).33	0.51	0.013	0.020	
).19	0.25	0.008	0.010	
0°	8 °	0°	8°	
).25	0.50	0.010	0.020	
Pin Features				
		8		
)		Pin Fe	Pin Features	

- 1. The chamfer on the body is optional. If it not present, a visual index feature, e.g. a dot, must be located within the cross—hatched area.

- 2. Controlling dimension are in inches.
 3. Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
 4. Dimension E1 do not include inter-lead flash or protusion. These shall not exceed 0.010" per side.
 5. Dimension b does not include dambar protusion/intrusion. Allowable dambar protusion shall be 0.004" total in excess of b dimension.

© Mitel							ORIGINATING SITE: SWINDON	
ISSUE	1	2	3	4				Title: Package Outline Drawing for 8 Ids SOIC(N)—0.150" Body Width (MP)
ACN	006745	201936	202595	203705		MITEL	SEMICONDUCTOR	8 las SOIC(N)—0.130 Body Width (MP)
DATE	5APR95	27FEB97	12JUN97	9DEC97				Drawing Number
APPROVED								GPD00010



http://www.mitelsemi.com

World Headquarters - Canada

Tel: +1 (613) 592 2122 Fax: +1 (613) 592 6909

Asia/Pacific

Tel: +65 333 6193 Fax: +65 333 6192 Europe, Middle East, and Africa (EMEA)

Tel: +44 (0) 1793 518528 Fax: +44 (0) 1793 518581

Information relating to products and services furnished herein by Mitel Corporation or its subsidiaries (collectively "Mitel") is believed to be reliable. However, Mitel assumes no liability for errors that may appear in this publication, or for liability otherwise arising from the application or use of any such information, product or service or for any infringement of patents or other intellectual property rights owned by third parties which may result from such application or use. Neither the supply of such information or purchase of product or service conveys any license, either express or implied, under patents or other intellectual property rights owned by Mitel or licensed from third parties by Mitel, whatsoever. Purchasers of products are also hereby notified that the use of product in certain ways or in combination with Mitel, or non-Mitel furnished goods or services may infringe patents or other intellectual property rights owned by Mitel.

This publication is issued to provide information only and (unless agreed by Mitel in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. The products, their specifications, services and other information appearing in this publication are subject to change by Mitel without notice. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. Manufacturing does not necessarily include testing of all functions or parameters. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to Mitel's conditions of sale which are available on request.

M Mitel (design) and ST-BUS are registered trademarks of MITEL Corporation Mitel Semiconductor is an ISO 9001 Registered Company Copyright 1999 MITEL Corporation All Rights Reserved Printed in CANADA

North America

Tel: +1 (770) 486 0194

Fax: +1 (770) 631 8213

TECHNICAL DOCUMENTATION - NOT FOR RESALE